



Product Change Notification

112903 - 00

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Should you have any issues with the timeline or content of this change, please contact the Intel Representative(s) for your geographic location listed below. No response from customers will be deemed as acceptance of the change and the change will be implemented pursuant to the key milestones set forth in this attached PCN.

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Product Change Notification

Change Notification #: 112903 - 00
Change Title: Intel® Server Chassis H2216XXKR and H2312XXKR
PCN 112903-00, Product Design Update Chassis Architecture
Date of Publication: February 26, 2014

Key Characteristics of the Change:

Product Design

Forecasted Key Milestones:

Date Customer Must be Ready to Receive Post-Conversion Material *:	Mar 14, 2014
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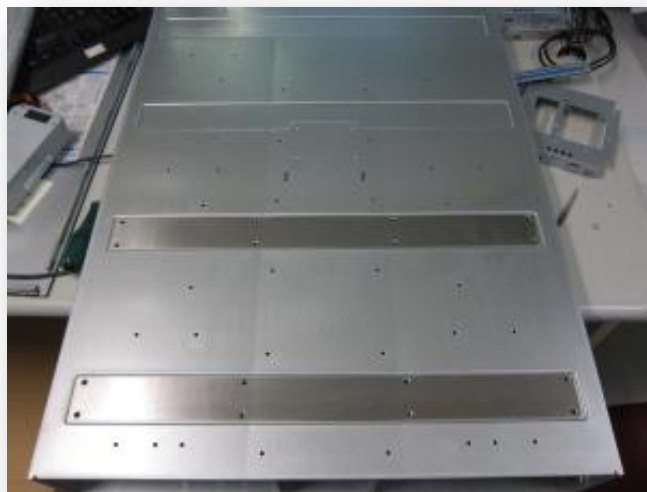
* Intel appreciates the customer's desire to receive the latest revision of products. However, Intel manages inventory on a first in first out (FIFO) basis at the MM# level. Subsequently, customer requests for a specific revision of material (below the MM#) will not be supported by Intel.

Description of Change to the Customer:

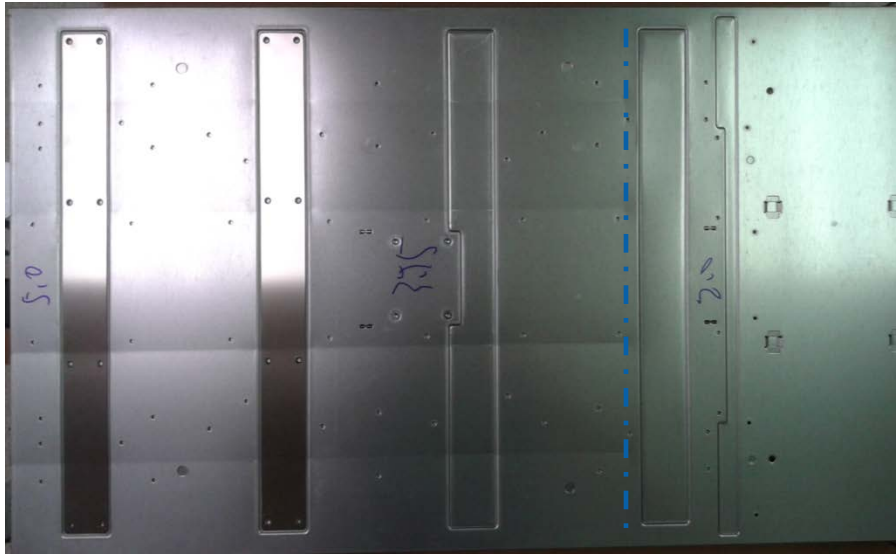
Intel is implementing the following changes on the Intel® Server Chassis H2216XXKR and H2312XXKR:

The chassis base architecture has been strengthened with the following updates so that the middle of the chassis will not sag when the system is installed in a rack.

1. Add four emboss areas on the chassis base with two stainless strips to strengthen the chassis base (see the picture below).



- When installed in the rack, the chassis will be pre-bent along the four crimping lines in the opposite direction of the potential chassis sag. The chassis will show a slight horizontal bow when empty, but will be completely horizontal when all modules and other components are installed in it. The crimping lines end at the blue line as shown below.



- Add five emboss areas on the rear of the top cover to strengthen the chassis to prevent the chassis sag.



4. Increase the height of the hot-swap backplane holder bracket bridges from 2mm to 3mm for adopting the chassis base pre-bending.



Customer Impact of Change and Recommended Action:

Intel suggests that customers perform a re-test with the new chassis material when made available.

Products Affected / Intel Ordering Codes:

Product Code	MM#	Pre Change TA	Post Change TA
H2312XXKR	919022	G68925-002	G68925-003
H2216XXKR	919023	G68928-002	G68928-003

PCN Revision History:

Date of Revision:
February 26, 2014

Revision Number:
00

Reason:
Originally Published PCN